

L Number	Hits	Search Text	DB	Time stamp
1	1	("20020160546").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:07
2	14734	photo adj resist	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:15
3	3895	trench adj fill\$2	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:09
4	53493	trench	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:09
5	22142	cmp	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:10
6	23096	planariz\$3	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:10
7	138	(photo adj resist) and (trench adj fill\$2)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:10
8	61	((photo adj resist) and (trench adj fill\$2)) and cmp	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:10
9	47	((((photo adj resist) and (trench adj fill\$2)) and cmp) and planariz\$3	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:10
10	266601	resist	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:15
11	14734	(photo adj resist) and resist	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:16
12	856	(trench adj fill\$2) and resist	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:16
13	351	cmp and ((trench adj fill\$2) and resist)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:16
14	254	(cmp and ((trench adj fill\$2) and resist)) and planariz\$3	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 13:17

15	2	("5173439" "5719073").PN.	USPAT	2002/11/25 13:39
16	1	6107187.URPN.	USPAT	2002/11/25 13:39
-	1	("0000424").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 13:47
-	49798	trench	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 13:47
-	389	trench and shore	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 13:48
-	4	(trench and shore) and (sti or (shallow adj trench adj isolation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 14:29
-	1055	(438/692).CCLS.	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/25 12:44
-	14	((438/692).CCLS.) and (shore or (shore adj D))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 14:35
-	3	((438/692).CCLS.) and (shore or (shore adj D)) and (sti or (shallow adj trench adj isolation))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 14:35
-	114633	(silicon adj (substrate or wafer))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 15:34
-	127	((silicon adj (substrate or wafer))) and (shore or (shore adj d))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 15:49
-	4	((silicon adj (substrate or wafer))) and (shore or (shore adj d)) and trench	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/05/28 15:49